



# THE DATASHEET OF IP4085CX4/LF/PHP



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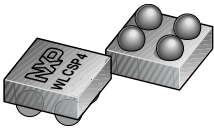
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Kind regards,

Team Nexperia



# IP4085CX4; IP4385CX4; IP4386CX4; IP4387CX4

Integrated high-performance ESD protection diodes

Rev. 2 — 14 December 2012

Product data sheet

## 1. Product profile

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### 1.1 General description

Integrated high-performance protection diodes protecting appliances against ElectroStatic Discharge (ESD) of  $\pm 30$  kV, far exceeding IEC 61000-4-2 level 4 standard, overvoltage and wrong polarity.

Each device includes one high-level ESD protection diode in a 4-channel 0.4 mm (IP438xCX4) or 0.5 mm (IP4085CX4) pitch Wafer Level Chip-Size Package (WLCSP). The anode and the cathode of ESD protection diode are each connected to two solder balls.

### 1.2 Features and benefits

- Single integrated high-performance ESD protection diode
- Surge immunity according to IEC 61000-4-5 (8/20  $\mu$ s) up to 60 A (IP4085CX4)
- ESD protection of >30 kV contact discharge, far exceeding IEC 61000-4-2, level 4
- Small  $2 \times 2$  solder ball WLCSP package with 0.4 mm or 0.5 mm pitch

### 1.3 Applications

General-purpose ESD protection such as for charger interfaces in:

- Mobile handsets
- Portable devices
- Wireless data systems



## 2. Pinning information

**Table 1. Pinning**

Pin	Description	Simplified outline	Graphic symbol
A1 and A2	cathode	<p>008aaa236</p> <p>transparent top view, solder balls facing down</p>	<p>006aad220</p>
B1 and B2	anode		

## 3. Ordering information

**Table 2. Ordering information**

Type number	Package		Version
	Name	Description	
IP4085CX4/LF/P	WLCSP4	wafer level chip-size package: 4 bumps (2 × 2) <sup>[1]</sup>	IP4085CX4/LF/P
IP4385CX4/LF		wafer level chip-size package: 4 bumps (2 × 2) <sup>[2]</sup>	IP4385CX4/LF
IP4386CX4/P			IP4386CX4/P
IP4387CX4/P			IP4387CX4/P

[1] Size: 0.91 × 0.91 × 0.65 mm

[2] Size: 0.76 × 0.76 × 0.61 mm

## 4. Limiting values

**Table 3. Limiting values**
*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>RWM</sub>	reverse standoff voltage	IP4085CX4; IP4386CX4	-0.5	+14	V
		IP4385CX4	-0.5	+5.5	V
		IP4387CX4	-0.5	+8.0	V
V <sub>ESD</sub>	electrostatic discharge voltage	all pins to ground			
		contact discharge	[1] -30	+30	kV
		air discharge	[1] -15	+15	kV
		IEC 61000-4-2, level 4; all pins to ground			
		contact discharge	-8	+8	kV
	air discharge	-15	+15	kV	
I <sub>PP</sub>	peak pulse current	IEC 61000-4-5; t <sub>p</sub> = 8/20 μs			
		IP4085CX4	60	-	A
		IP4385CX4; IP4387CX4	33	-	A
		IP4386CX4	28	-	A
I <sub>FSM</sub>	non-repetitive peak forward current	10 pulses; 1 pulse per second			
		IP4085CX4; IP4386CX4; t <sub>p</sub> = 2 ms	10	-	A
		IP4085CX4; IP4386CX4; t <sub>p</sub> = 5 ms	8.5	-	A
		IP4085CX4; IP4386CX4; t <sub>p</sub> = 100 ms	3.5	-	A
		IP4385CX4; IP4387CX4; t <sub>p</sub> = 2 ms	11	-	A
		IP4385CX4; IP4387CX4; t <sub>p</sub> = 5 ms	9	-	A
		IP4385CX4; IP4387CX4; t <sub>p</sub> = 100 ms	5	-	A
P <sub>tot</sub>	total power dissipation	forward conducting	[2]		
		IP4085CX4	[3] -	1	W
		IP4385CX4; IP4386CX4; IP4387CX4	[3] -	0.7	W
T <sub>stg</sub>	storage temperature		-55	+150	°C
T <sub>reflow(peak)</sub>	peak reflow temperature	t <sub>p</sub> ≤ 10 s	-	260	°C
T <sub>amb</sub>	ambient temperature		-30	+85	°C

[1] Device tested with over 1000 pulses of ±30 kV contact discharges, according to the IEC 61000-4-2 model.

[2] Severe self-heating demands a heat-dissipation optimized Printed-Circuit Board (PCB) to prevent the device from de-soldering. For ambient temperature above 50 °C, the guaranteed life time is 48 hours at 0.7 W, assuming R<sub>th</sub> to be 130 K/W as specified in [Table 4](#).

[3] Permanent operation at maximum power dissipation and above maximum junction temperature will result in a reduced life time.

## 5. Thermal characteristics

**Table 4. Thermal characteristics**

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	on a 2-layer PCB	[1] 130	K/W

[1] Depends on details of PCB layout.

## 6. Characteristics

**Table 5. Electrical characteristics**

$T_{amb} = 25\text{ °C}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{BR}$	breakdown voltage	$I_R = 15\text{ mA}$				
		IP4085CX4; IP4386CX4	16	-	-	V
		IP4385CX4	7.0	-	-	V
		IP4387CX4	10	-	-	V
$V_{CL}$	clamping voltage	$I_R = 1\text{ A}$ ; $T_{amb} \leq 85\text{ °C}$ at surge peak pulse, according to IEC 61000-4-5				
		IP4085CX4	-	-	20	V
		IP4385CX4	-	-	10	V
		IP4386CX4	-	-	20	V
$I_{RM}$	reverse leakage current	IP4085CX4; IP4385CX4 $V_R = +5\text{ V}$	-	-	200	nA
		IP4386CX4; $V_R = +14\text{ V}$	-	-	200	nA
		IP4387CX4; $V_R = +8\text{ V}$	-	-	800	nA
$C_d$	diode capacitance	$V_R = 0\text{ V}$ ; $f = 1\text{ MHz}$				
		IP4085CX4	-	180	-	pF
		IP4385CX4	-	450	-	pF
		IP4386CX4	-	160	-	pF
$V_F$	forward voltage	$I_F = 850\text{ mA}$				
		IP4085CX4	[1] -	-	1.15	V
			[2] -	-	1.3	V
		IP4385CX4	[1] -	-	1.0	V
			[2] -	-	1.1	V
		IP4386CX4	[1] -	-	1.15	V
			[2] -	-	1.3	V
		IP4387CX4	[1] -	-	1.10	V
[2] -	-		1.25	V		

[1]  $T_{amb} \geq +25\text{ °C}$

[2]  $-30\text{ °C} \leq T_{amb} \leq +85\text{ °C}$

## 7. Application information

### 7.1 Forward current DC clamping voltage

The forward current DC clamping voltage is an indicator of protection level of circuit from voltage sources with the wrong polarity. [Figure 1](#) shows basic measurement setup.

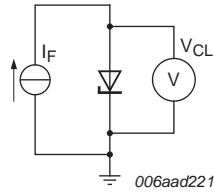
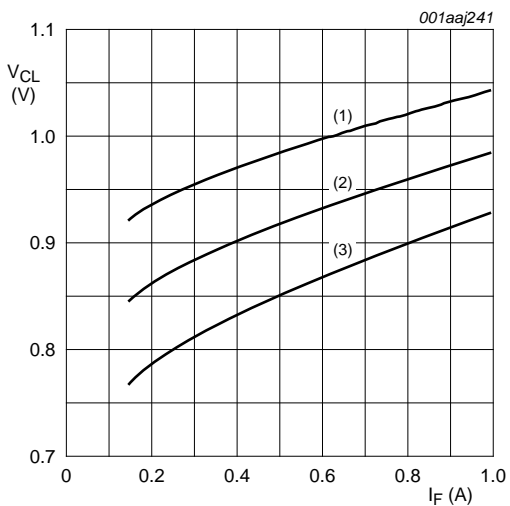
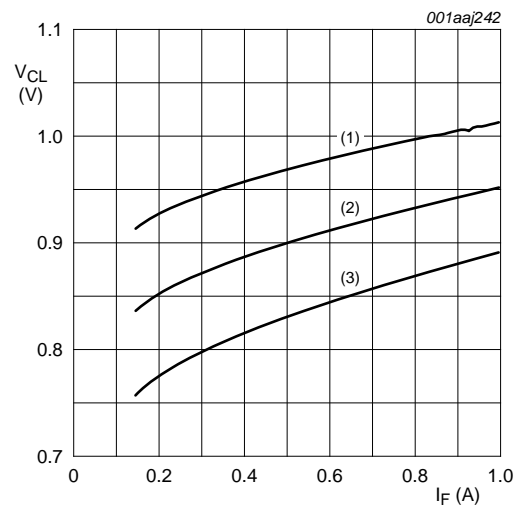


Fig 1. Measuring DC clamping voltage with forward current



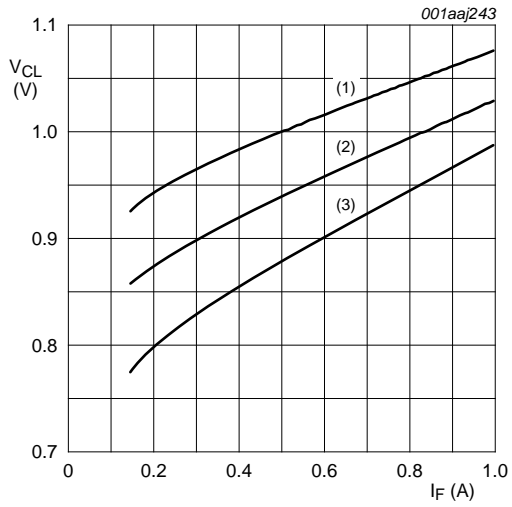
- (1)  $T_{amb} = +25\text{ °C}$
- (2)  $T_{amb} = +85\text{ °C}$
- (3)  $T_{amb} = -30\text{ °C}$

Fig 2. IP4085CX4: DC clamping voltage as a function of forward current



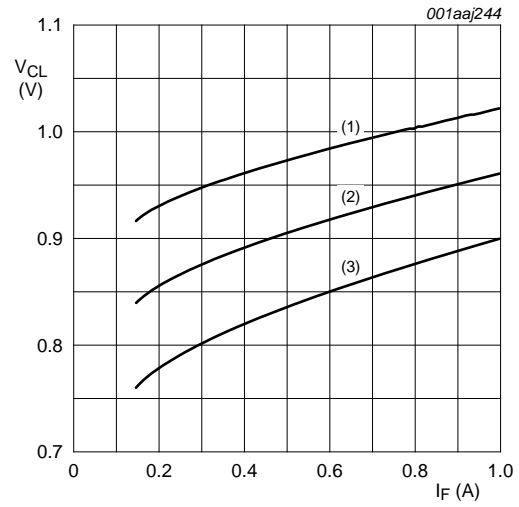
- (1)  $T_{amb} = +25\text{ °C}$
- (2)  $T_{amb} = +85\text{ °C}$
- (3)  $T_{amb} = -30\text{ °C}$

Fig 3. IP4385CX4: DC clamping voltage as a function of forward current



- (1)  $T_{amb} = +25\text{ °C}$
- (2)  $T_{amb} = +85\text{ °C}$
- (3)  $T_{amb} = -30\text{ °C}$

Fig 4. IP4386CX4: DC clamping voltage as a function of forward current



- (1)  $T_{amb} = +25\text{ °C}$
- (2)  $T_{amb} = +85\text{ °C}$
- (3)  $T_{amb} = -30\text{ °C}$

Fig 5. IP4387CX4: DC clamping voltage as a function of forward current

### 7.2 Peak clamping voltage

The peak clamping voltage for forward and reverse current pulses of 8/20  $\mu\text{s}$  (IEC 61000-4-5) is an indicator of protection level of circuits from power surges due to voltage discharges. The current pulse shape over time is shown in [Figure 7](#). The basic measurement setup for forward current and reverse current pulses respectively are shown in [Figure 6](#) and [Figure 12](#).

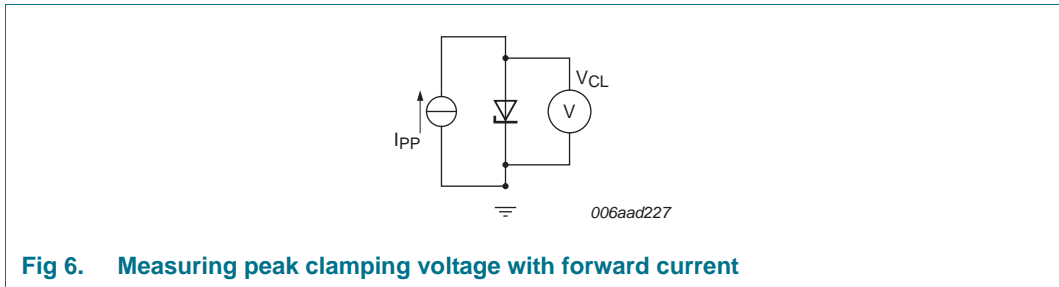


Fig 6. Measuring peak clamping voltage with forward current

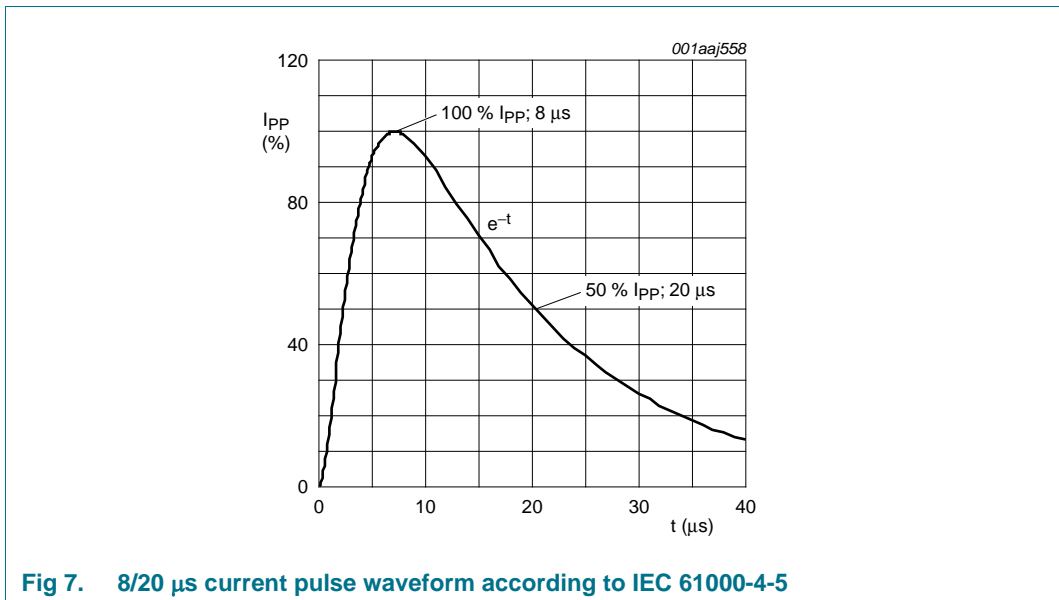
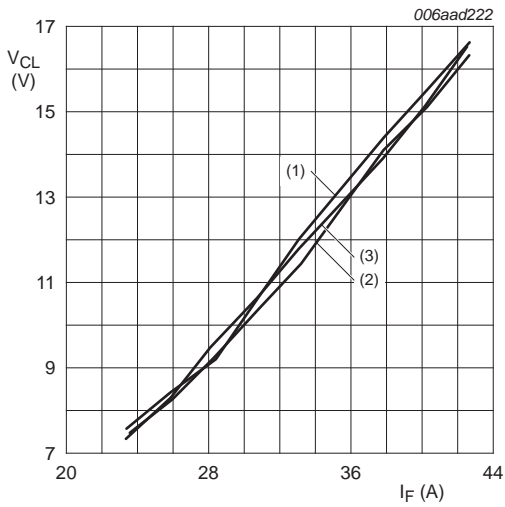
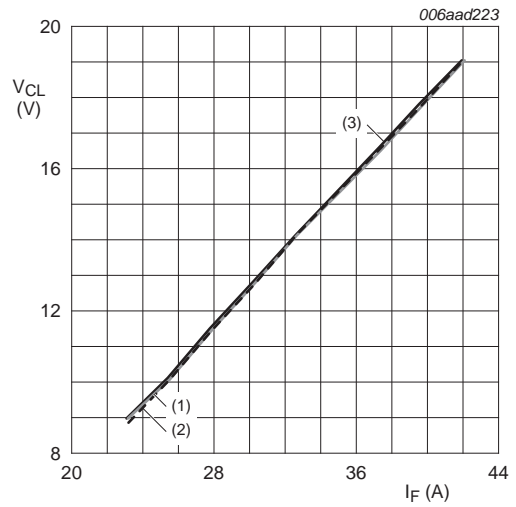


Fig 7. 8/20  $\mu\text{s}$  current pulse waveform according to IEC 61000-4-5



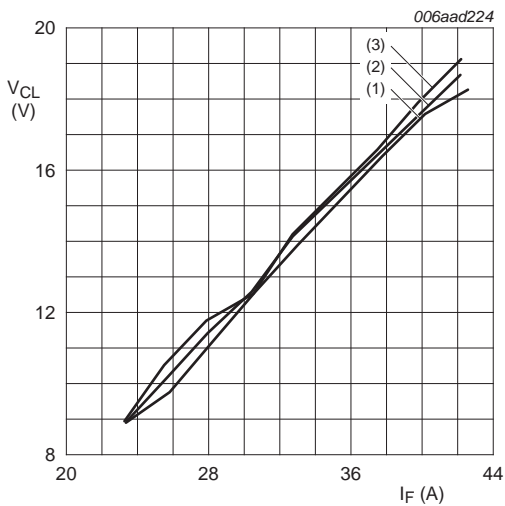
- (1)  $T_{amb} = +25\text{ }^{\circ}\text{C}$
- (2)  $T_{amb} = +85\text{ }^{\circ}\text{C}$
- (3)  $T_{amb} = -30\text{ }^{\circ}\text{C}$

Fig 8. IP4085CX4: peak clamping voltage as a function of forward current



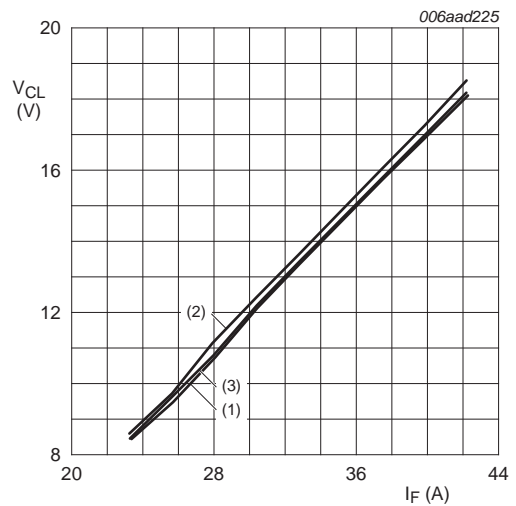
- (1)  $T_{amb} = +25\text{ }^{\circ}\text{C}$
- (2)  $T_{amb} = +85\text{ }^{\circ}\text{C}$
- (3)  $T_{amb} = -30\text{ }^{\circ}\text{C}$

Fig 9. IP4385CX4: peak clamping voltage as a function of forward current



- (1)  $T_{amb} = +25\text{ }^{\circ}\text{C}$
- (2)  $T_{amb} = +85\text{ }^{\circ}\text{C}$
- (3)  $T_{amb} = -30\text{ }^{\circ}\text{C}$

Fig 10. IP4386CX4: peak clamping voltage as a function of forward current



- (1)  $T_{amb} = +25\text{ }^{\circ}\text{C}$
- (2)  $T_{amb} = +85\text{ }^{\circ}\text{C}$
- (3)  $T_{amb} = -30\text{ }^{\circ}\text{C}$

Fig 11. IP4387CX4: peak clamping voltage as a function of forward current

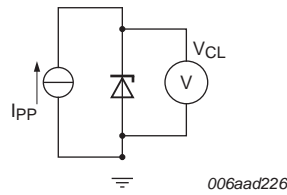
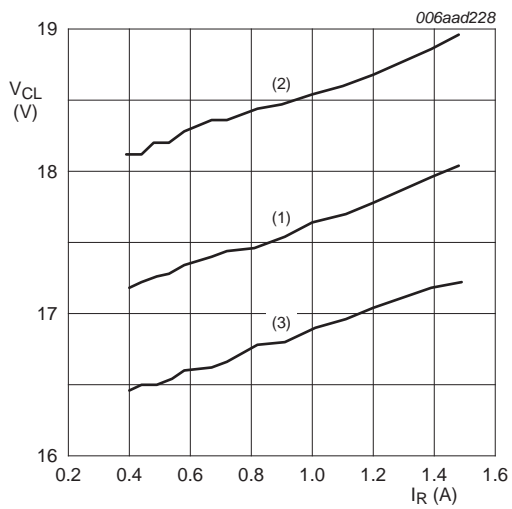
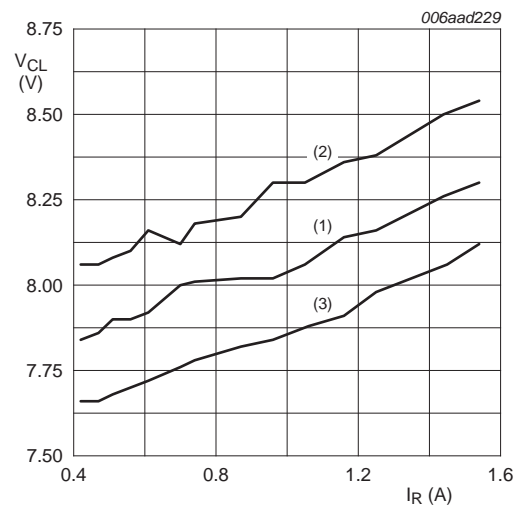


Fig 12. Measuring peak clamping voltage with reverse current



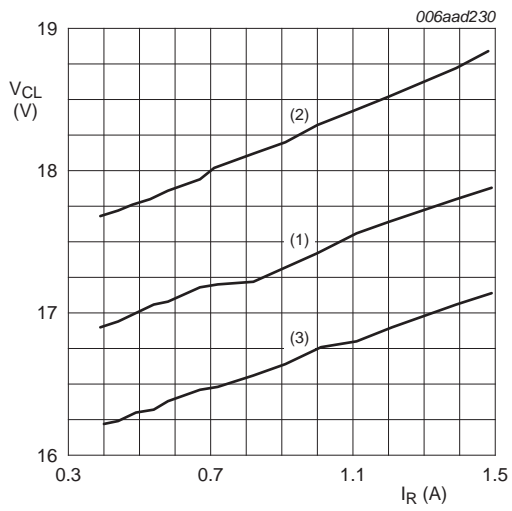
- (1)  $T_{amb} = +25\text{ }^{\circ}\text{C}$
- (2)  $T_{amb} = +85\text{ }^{\circ}\text{C}$
- (3)  $T_{amb} = -30\text{ }^{\circ}\text{C}$

Fig 13. IP4085CX4: peak clamping voltage as a function of reverse current



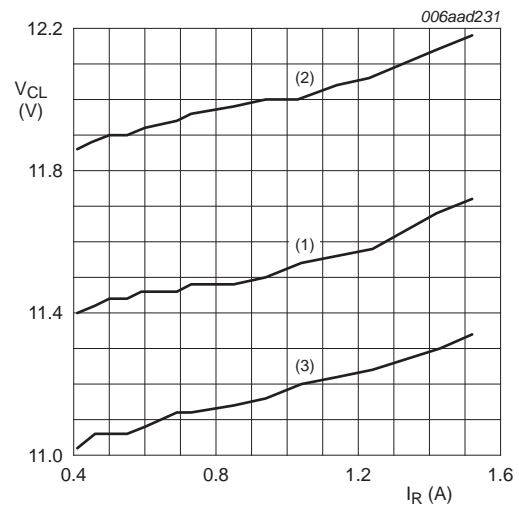
- (1)  $T_{amb} = +25\text{ }^{\circ}\text{C}$
- (2)  $T_{amb} = +85\text{ }^{\circ}\text{C}$
- (3)  $T_{amb} = -30\text{ }^{\circ}\text{C}$

Fig 14. IP4385CX4: peak clamping voltage as a function of reverse current



- (1)  $T_{amb} = +25\text{ }^{\circ}\text{C}$ .
- (2)  $T_{amb} = +85\text{ }^{\circ}\text{C}$ .
- (3)  $T_{amb} = -30\text{ }^{\circ}\text{C}$ .

Fig 15. IP4386CX4: peak clamping voltage as a function of reverse current

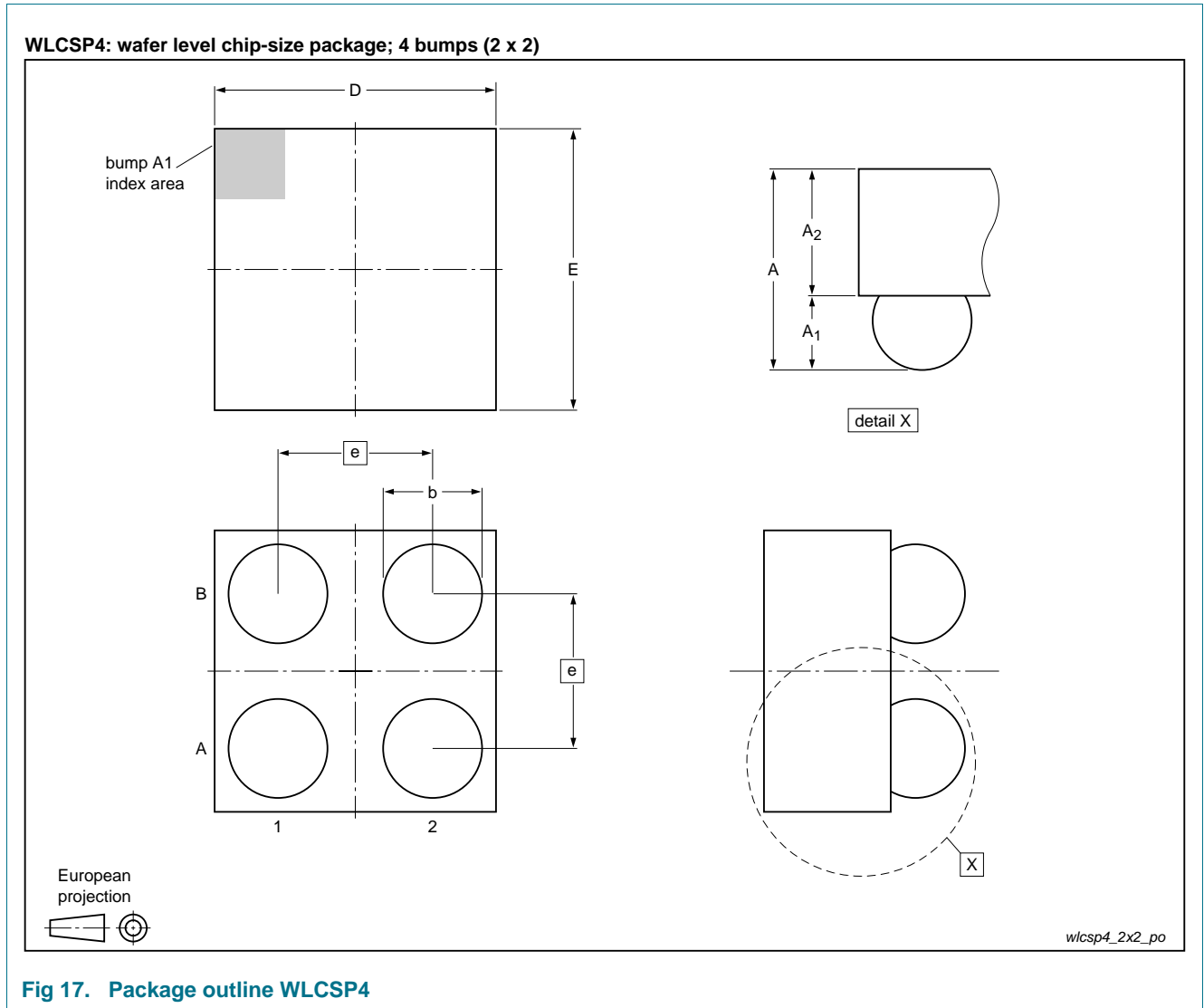


- (1)  $T_{amb} = +25\text{ }^{\circ}\text{C}$ .
- (2)  $T_{amb} = +85\text{ }^{\circ}\text{C}$ .
- (3)  $T_{amb} = -30\text{ }^{\circ}\text{C}$ .

Fig 16. IP4387CX4: peak clamping voltage as a function of reverse current

Measurements are done on a heat-dissipation optimized PCB with massive copper area under the Device Under Test (DUT).

## 8. Package outline



**Table 6. Package outline dimensions of IP4085CX4 (WLCSP4)**

Symbol	Min	Typ	Max	Unit
A	0.60	0.65	0.70	mm
A <sub>1</sub>	0.22	0.24	0.26	mm
A <sub>2</sub>	0.38	0.41	0.44	mm
b	0.27	0.32	0.37	mm
D	0.86	0.91	0.96	mm
E	0.86	0.91	0.96	mm
e	0.5	0.5	0.5	mm

Table 7. Package outline dimensions of IP438xCX4 (WLCSP4)

Symbol	Min	Typ	Max	Unit
A	0.56	0.61	0.66	mm
A <sub>1</sub>	0.18	0.20	0.22	mm
A <sub>2</sub>	0.38	0.41	0.44	mm
b	0.21	0.26	0.31	mm
D	0.71	0.76	0.76	mm
E	0.71	0.76	0.81	mm
e	0.4	0.4	0.4	mm

## 9. Design and assembly recommendations

### 9.1 PCB design guidelines

For optimum performance, use a Non-Solder Mask Defined (NSMD), also known as a copper-defined design, incorporating laser-drilled micro-vias connecting the ground pads to a buried ground-plane layer. This results in the lowest possible ground inductance and provides the best high frequency and ESD performance. Refer to [Table 8](#) for the recommended PCB design parameters.

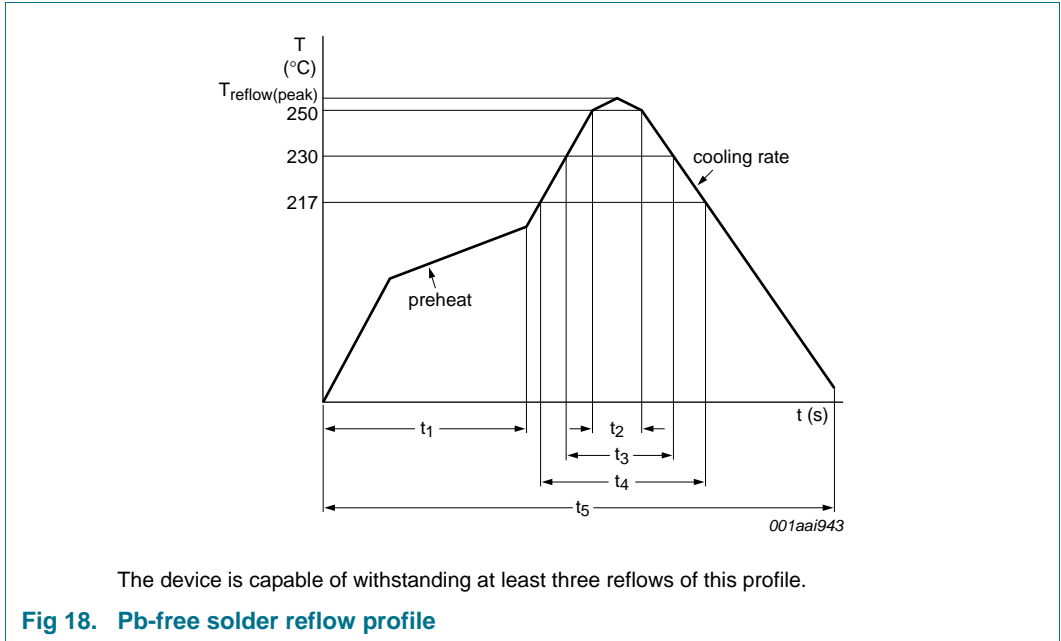
Table 8. Recommended PCB design parameters

Parameter	Value or Specification
PCB pad diameter	200 μm
Micro-via diameter	100 μm (0.004 inch)
Solder mask aperture diameter	370 μm
Copper thickness	20 μm to 40 μm
Copper finish	AuNi
PCB material	FR4

### 9.2 PCB assembly guidelines for Pb-free soldering

Table 9. Assembly recommendations

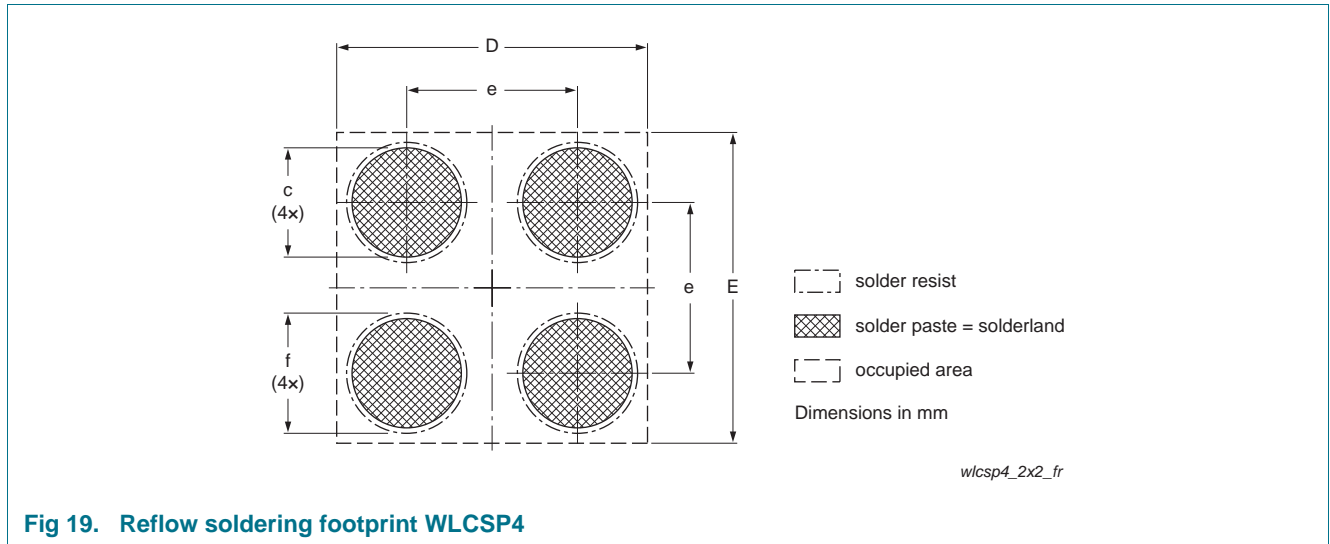
Parameter	Value or Specification
Solder screen aperture diameter	330 μm
Solder screen thickness	100 μm (0.004 inch)
Solder paste: Pb-free	SnAg (3 % to 4 %) Cu (0.5 % to 0.9 %)
Solder to flux ratio	50 : 50
Solder reflow profile	see <a href="#">Figure 18</a>



**Table 10. Reflow soldering process characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{\text{reflow(peak)}}$	peak reflow temperature		230	-	260	°C
$t_1$	time 1	soak time	60	-	180	s
$t_2$	time 2	time during $T \geq 250$ °C	-	-	30	s
$t_3$	time 3	time during $T \geq 230$ °C	10	-	50	s
$t_4$	time 4	time during $T > 217$ °C	30	-	150	s
$t_5$	time 5		-	-	540	s
$dT/dt$	rate of change of temperature	cooling rate	-	-	-6	°C/s
		pre-heat	2.5	-	4.0	°C/s

## 10. Soldering



**Fig 19. Reflow soldering footprint WLCSP4**

**Table 11. Soldering dimensions of IP4085CX4 (WLCSP4)**

Symbol	Min	Typ	Max	Unit
c	-	0.31	-	mm
D	0.86	0.91	0.96	mm
E	0.86	0.91	0.96	mm
e	-	0.5	-	mm
f	-	0.385	-	mm

**Table 12. Soldering dimensions of IP438xCX4 (WLCSP4)**

Symbol	Min	Typ	Max	Unit
c	-	0.25	-	mm
D	0.71	0.76	0.81	mm
E	0.71	0.76	0.81	mm
e	-	0.4	-	mm
f	-	0.325	-	mm

## 11. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
IP4085_4385_4386_4387_CX4 v.2	20121214	Product data sheet	-	IP4085_4385_4386_4387_CX4 v.1
Modifications:			<ul style="list-style-type: none"> <li>• Basic type IP4085CX4/LF removed</li> <li>• <a href="#">Section 1 “Product profile”</a>: updated</li> <li>• <a href="#">Section 2 “Pinning information”</a>: updated</li> <li>• Functional diagram: removed</li> <li>• <a href="#">Table 3 “Limiting values”</a>: updated</li> <li>• <a href="#">Table 5 “Electrical characteristics”</a>: updated</li> <li>• <a href="#">Section 7 “Application information”</a>: updated</li> <li>• <a href="#">Figure 1, 6, 8 to 16</a>: updated</li> <li>• Marking: removed</li> <li>• <a href="#">Section 8 “Package outline”</a>: updated</li> <li>• <a href="#">Section 10 “Soldering”</a>: added</li> <li>• <a href="#">Section 12 “Legal information”</a>: updated</li> </ul>	
IP4085_4385_4386_4387_CX4 v.1	20090326	Product data sheet	-	-

## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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